REVISION A

DO NOT SCALE FROM THIS PRINT
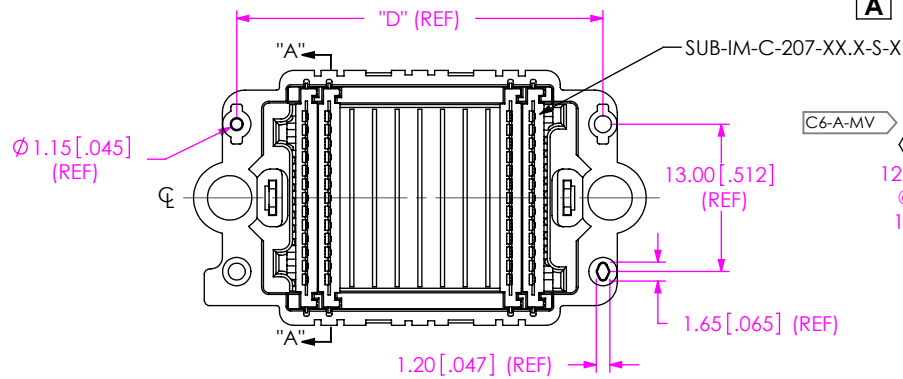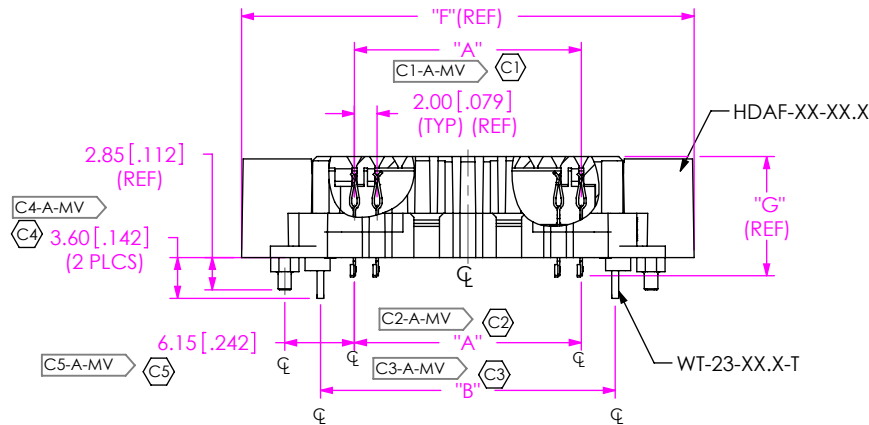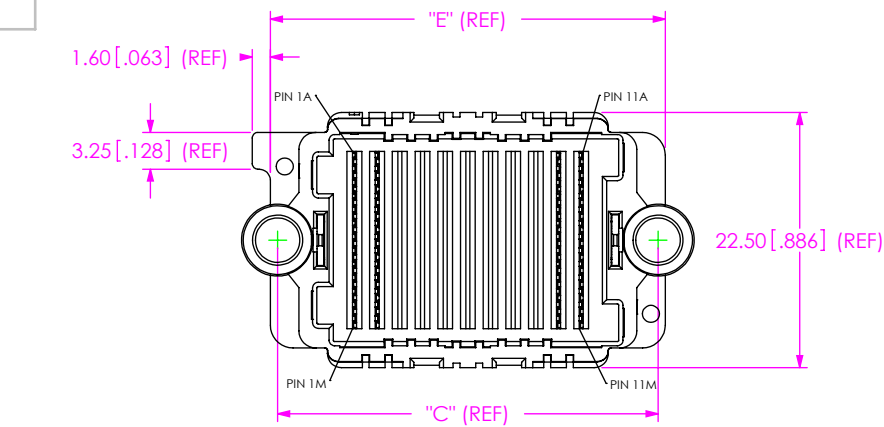
"E" (REF)
1.60 [.063] (REF)
3.25 [.128] (REF)
PIN 1A
PIN 11A
22.50 [.886] (REF)
PIN 1M
PIN 11M
"C" (REF)

HDAF-XX-XX.X-X-13-X-X

OPTION
-P: PICK & PLACE PAD
(USE MPP-26-01-N)

No OF POSITIONS
(13 ROWS PER POSITION)
-11
-15
-23

SOLDER CHARGE MATERIAL
-1: 63% TIN / 37% LEAD
-2: 95.5% TIN / 3.8% SILVER
0.7% COPPER (LEAD FREE)

LEAD STYLE
-08.0: 8MM
-18.0: 18MM

No OF ROWS
-13

PLATING SPECIFICATION
-S: SELECTIVE, .000030 INCHES GOLD IN MATING AREA,
MATTE TIN ON TAIL AND WELD TABS

"F" (REF)
"A"
C1-A-MV C1
2.00 [.079] (TYP) (REF)
HDAF-XX-XX.X
2.85 [.112] (REF)
C4-A-MV C4
3.60 [.142] (2 PLCS)
"G" (REF)
C2-A-MV C2
"A"
WT-23-XX.X-T
6.15 [.242]
C5-A-MV C5
C3-A-MV C3
"B"

TABLE 1

STYLE	"BODY CALLOUT"	"CONTACT WAFER"	"SOLDER NAIL"
-08.0	HDAF-XX-08.0	SUB-IM-C-207-08.0-S-X	WT-23-08.0-T
-18.0	HDAF-XX-18.0	SUB-IM-C-207-18.0-S-X	WT-23-18.0-T

A

TABLE 2

STACK HEIGHT

HDAF LEAD STYLE	HDAM LEAD STYLE	
	-12.0	-17.0
-08.0	20.0MM	25.0MM
-18.0	30.0MM	35.0MM
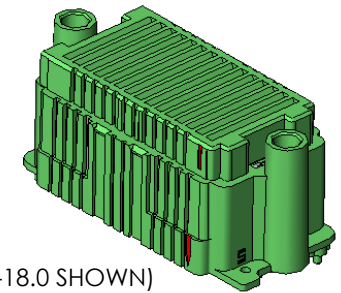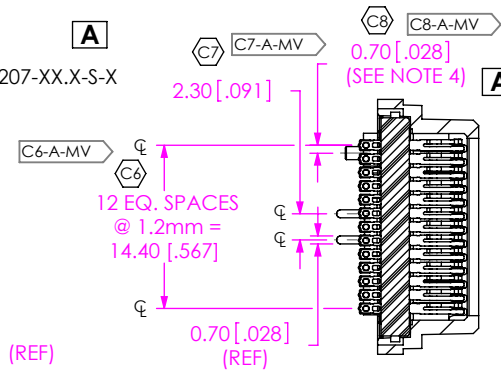
(-18.0 SHOWN)

"D" (REF)
"A"
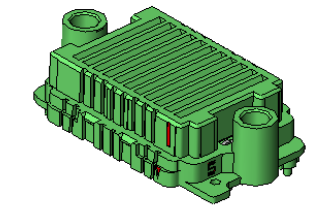SUB-IM-C-207-XX.X-S-X
Ø 1.15 [.045] (REF)
13.00 [.512] (REF)
"A"
1.65 [.065] (REF)
1.20 [.047] (REF)

C8 C8-A-MV
C7 C7-A-MV
0.70 [.028] (SEE NOTE 4)
2.30 [.091]
A
C6-A-MV
C6
12 EQ. SPACES @ 1.2mm = 14.40 [.567]
0.70 [.028] (REF)
SECTION "A"-"A"

(-08.0 SHOWN)

FIG. 1
-11: 11 POSITION
(HDAF-11-08.0-X-13-X-X SHOWN)
(SOME WAFERS NOT SHOWN FOR CLARITY)

NOTES:
1. Ⓒ REPRESENTS A CRITICAL DIMENSION.
2. MINIMUM PUSHOUT FORCE: 2.22N[.5 LB]. FOR WAFERS AND WELD TABS.
3. CONNECTORS TO BE PACKAGED IN TRAYS.
4. DIMENSION FROM ℄ OF END TAIL TO ℄ OF -A PIN.
A

DESIGNED & DIMENSIONED
IN MILLIMETERS
(INCHES FOR REFERENCE ONLY)

SAMTEC
520 PARK EAST BLVD, NEW ALBANY, IN 47150
* PHONE: 812.944.6733   FAX: 812.948.5047
e-Mail: INFO@SAMTEC.COM   CODE: 55322

MATERIAL: DO NOT SCALE DRAWING
INSULATOR: LCP   COLOR: BLACK
CONTACT: COPPER ALLOY
WAFER MATERIAL: LCP, COLOR: BLACK
PICK AND PLACE PAD: COPPER ALLOY
WELD TAB: BRASS

SHEET SCALE: 1.5:1

DESIGNED WITH SolidWorks

DESCRIPTION:
2.0MM PITCH HD ARRAY SOCKET ASSEMBLY
DWG. NO.
HDAF-XX-XX.X-X-13-X-X

F:\DWG\MISC\MKTG\HDAF-XX-XX.X-X-13-X-X-MKT.SLDDRW

BY: D KNOWLDEN   7/14/2005   SHEET 1 OF 2

TABLE 3

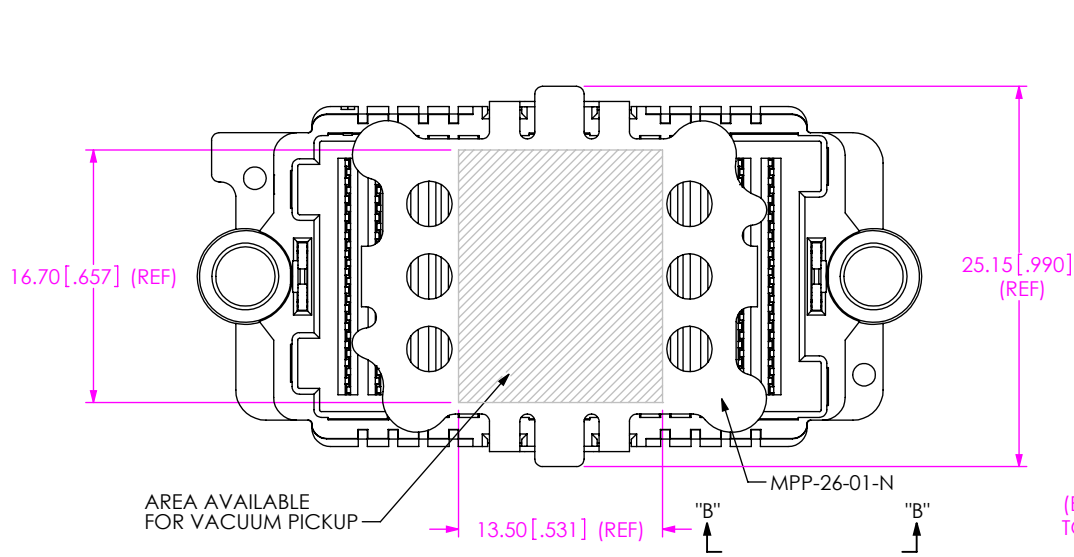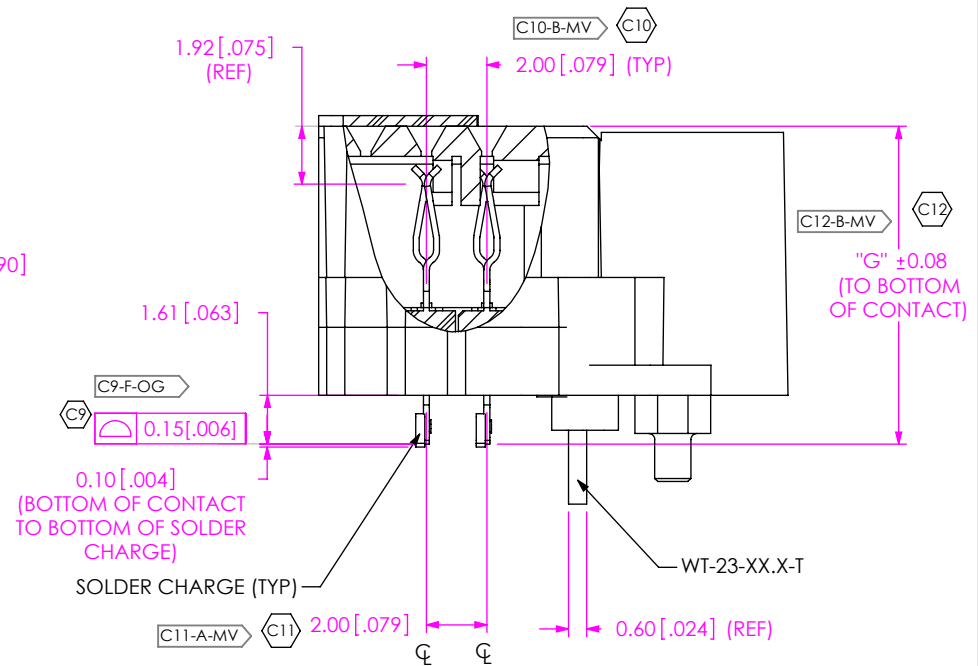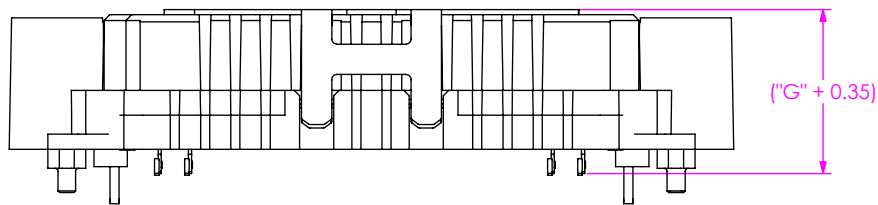| No. OF POS.	LEAD STYLE	"A"	"B"	"C"	"D"	"E"	"F"	"G"
11	08.0	20.0 [.787]	26.0 [1.02]	33.55 [1.321]	32.30 [1.272]	34.82 [1.371]	39.92 [1.572]	10.51 [.414]
15	08.0	28.0 [1.102]	34.0 [1.34]	41.55 [1.636]	40.30 [1.587]	42.82 [1.686]	47.92 [1.887]	10.51 [.414]
23	08.0	44.0 [1.732]	50.0 [1.97]	57.55 [2.266]	56.30 [2.217]	58.82 [2.316]	63.92 [2.517]	10.51 [.414]
11	18.0	20.0 [.787]	26.0 [1.02]	33.55 [1.321]	32.30 [1.272]	34.82 [1.371]	39.92 [1.572]	20.51 [.807]
15	18.0	28.0 [1.102]	34.0 [1.34]	41.55 [1.636]	40.30 [1.587]	42.82 [1.686]	47.92 [1.887]	20.51 [.807]
23	18.0	44.0 [1.732]	50.0 [1.97]	57.55 [2.266]	56.30 [2.217]	58.82 [2.316]	63.92 [2.517]	20.51 [.807]

FIG. 2
-15: 15 POSITION
(HDAF-15-08.0-X-13-X-P SHOWN)
(SOME WAFERS NOT SHOWN FOR CLARITY)

AREA AVAILABLE
FOR VACUUM PICKUP

16.70 [.657] (REF)

25.15 [.990] (REF)

13.50 [.531] (REF)

MPP-26-01-N

"B"

("G" + 0.35)

VIEW "B"-"B"
SCALE 4:1

1.92 [.075] (REF)

2.00 [.079] (TYP)

C10-B-MV   C10

C12-B-MV   C12

"G" ±0.08
(TO BOTTOM
OF CONTACT)

1.61 [.063]

C9-F-OG

C9   0.15 [.006]

0.10 [.004]
(BOTTOM OF CONTACT
TO BOTTOM OF SOLDER
CHARGE)

SOLDER CHARGE (TYP)

C11-A-MV   C11   2.00 [.079]

0.60 [.024] (REF)

WT-23-XX.X-T

CRITICAL DIMENSION INSPECTION INSTRUCTION TABLE		
ASSEMBLY OPERATION	START-UP INSPECTION INSPECT CODE A	IN-PROCESS INSPECTION INSPECT CODE B
FILL WAFER	C1, C2, C5, C6, C8, C11	C10, C12
FILL WELD TABS	C2, C3, C4, C5, C11	C12
INSTALL PAD	C2, C5, C11	N/A

DO NOT SCALE DRAWING

SHEET SCALE: 1:1

SAMTEC

520 PARK EAST BLVD, NEW ALBANY, IN 47150
* PHONE: 812.944.6733   FAX: 812.948.5047
e-Mail: INFO@SAMTEC.COM   CODE: 55322

DESCRIPTION:
2.0MM PITCH HD ARRAY SOCKET ASSEMBLY

DWG. NO.
HDAF-XX-XX.X-X-13-X-X

BY:D KNOWLDEN   7/14/2005   SHEET 2 OF 2